

ABSTRACT

The present invention provides a wire saw for use in cutting works of electronics materials or optical materials and a method for manufacturing the same, said wire saw having the following characteristic features. Namely, onto a high-strength core wire 2, abrasive grains 3 having a grain size not smaller than two-thirds the thickness of a layer of resin bond 4 on said core wire 2 but not exceeding a half the diameter of said core wire are fixed with said resin bond, said resin bond containing a filler having a grain size smaller than two-thirds the thickness of said resin bond layer. The thus structured and arranged wire saw has an improved efficiency and precision in cutting. The wire saw can be manufactured readily by using an enamelling oven.